



제 31회 한국반도체학술대회

The 31st Korean Conference on Semiconductors

2024년 1월 24일(수)-26일(금) | 경주화백컨벤션센터(HICO)

2024년 1월 26일(금), 09:00-10:45

Room J(204), 2층

A. Interconnect & Package 분과

[FJ1-A] Advanced Packaging II

좌장: 김주영 교수(울산과학기술원), 안상훈 수석(삼성전자)

<p>FJ1-A-1 09:00-09:15</p>	<p>Electrochemical Study on Better Controllability of Cu Pad Topography in Cu/Ti CMP Seonwoo Go¹, Yoonji Ra¹, Jenasree Hazarika¹, Jum-Yong Park², Un-Byoung Kang², Tae-Gon Kim¹, and Jin-Goo Park¹ ¹Department of Materials Science and Chemical Engineering, Hanyang University ERICA, ²AVP Process Development Team, Samsung Electronics Co., Ltd.</p>
<p>FJ1-A-2 09:15-09:30</p>	<p>Optimization of Chemical Mechanical Polishing (CMP) for Die-to-Wafer Hybrid Bonding and the Impact of the SiCN Dielectric Layer Yeon Ju Kim, Sang Woo Park, Min Seong Jung, Ji Hun Kim, and Jong Kyung Park Department of Semiconductor Engineering, Seoul National University of Science and Technology</p>
<p>FJ1-A-3 09:30-09:45</p>	<p>3차원 반도체 패키지를 위한 저온 Cu-Cu 접합용 CuAg 합금 소재 및 신뢰성 평가 이승혁, 전주원, 마지수, 이용규, 김병준 한국공학대학교 신소재공학과</p>
<p>FJ1-A-4 09:45-10:00</p>	<p>Ar Carrier Gas SiN Film Deposition Process Optimization for WLPKG Chip Warpage Control Intae Whoang, Byung Yoon Lim, Jin Pyung Kim, Kijun Bang, and Seunghee Jo SK hynix</p>
<p>FJ1-A-5 10:00-10:15</p>	<p>The Impact of Surface Treatment on SiO₂ Bonding for Cu/SiO₂ Hybrid Bonding Injoo Kim¹, Siye Lee², Wookyung Lee², and Sungdong Kim² ¹Department of Mechanical Design and Robot Engineering, Seoul National University of Science and Technology, ²Department of Mechanical System Design Engineering, Seoul National University of Science and Technology</p>
<p>FJ1-A-6 10:15-10:30</p>	<p>Machine Learning-Based MI Image Classification for A.I Semiconductor Production Sung Hyun Yoon and Sang Yup Lee SK hynix</p>



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FJ1-A-7

10:30-10:45

Study on the Chemical Durability and Defect Reduction Effects of Ceramic-Based CVD CMP Conditioners

Yeon-Je Gye¹, Joo-Han Lee², Sun-Gyu Park², Yu-Jeong Jin², Jin-Goo Park¹, and Tae-Gon Kim¹

¹Department of Materials Science and Chemical Engineering, Hanyang University ERICA, ²Technical Development Electronics BU, EHWA DIAMOND INDUSTRIAL CO. LTD.